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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/756,971
Filing Date January 9, 2001
Inventor Salman Akram
Assignee Micron Technology, Inc.
Group Art Unit 2812
Examiner Jones, J.
Attorney's Docket No. MI22-1572
Title: Methods of Forming Board-On-Chip Packages

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

To: Assistant Commissioner for Patents
Washington, D.C. 20231

From: David G. Latwesen, Ph.D.
(Tel. 509-624-4276; Fax 509-838-3424)
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Dear Sir:

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449 and copies of which are attached.

Citation of these references is respectfully requested.

A check in the amount of \$180.00 is enclosed to cover the fee specified under 37 C.F.R. § 1.17(p).

09/756,971, TECHNICAL DISCLOSURE STATEMENT

01.17.17

180.00 (P)

Respectfully submitted,

Dated:

1/29/02

By:

[Signature]

David G. Latwesen, Ph.D.
Reg. No. 38,533